

# CHEMTRONICS® Technical Data Sheet

**TDS # SWick**

## Soder-Wick® Desoldering Braid

### PRODUCT DESCRIPTION

Soder-Wick® offers the state of the art in desoldering technology. Soder-Wick® is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage. A full range of sizes and flux types are available, including Rosin, No Clean, unfluxed and a high temperature Lead-Free version. Whatever the requirement, Soder-Wick® has the answer.


- Requires little or no post solder cleaning
- No corrosive residues
- Optimized construction for faster wicking and heat transfer
- Halide free
- Minimizes the risk of heat damage to components and circuit boards

### TYPICAL APPLICATIONS

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

### TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

<b>Flux Types:</b>	Rosin Grade WW, Type "R" Patented No Clean High Temperature No Clean		
<b>Specifications:</b>	ANSI/IPC J STD-004 MIL-F-14256 F		
<b>No Clean Flux Spec:</b>	MIL-STD-883B Bellcore TR-NWT-000078 ANSI/IPC J SF818		
<b>Shelflife:</b>	2 years		
<b>RoHS/WEEE Status</b>			
<b>Size #</b>	<b>Width Inches</b>	<b>Color</b>	<b>Width Metric</b>
1	.030"	White	0.8mm
2	.060"	Yellow	1.5mm
3	.080"	Green	2.0mm
4	.110"	Blue	2.8mm
5	.145"	Brown	3.7mm
6	.210"	Red	5.3mm
BGA	-	Purple	-

### STATIC DISSIPATIVE PACKAGING

Soder-Wick® SD is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

## USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick<sup>®</sup> desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks<sup>®</sup> Flux Remover Pen and remove soils with a ControlWipes<sup>™</sup> absorbent wipe.

## SODER-WICK<sup>®</sup> IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R  
NASA-STD-8739.3  
DOD-STD-883E, Method 2022  
ANSI/IPC J STD-004, Type ROL0  
BELLCORE TR-NWT-000078  
ANSI/IPC J SF-818

## SODER-WICK<sup>®</sup> SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A  
MIL-B-81705C  
MIL-STD-1686C  
MIL-HDBK-263B

## TECHNICAL & APPLICATION ASSISTANCE

Chemtronics<sup>®</sup> provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

## AVAILABILITY

### Series:

- 40 Soder-Wick<sup>®</sup> Lead-Free, SD Bobbin
- 50 Soder-Wick<sup>®</sup> Rosin
- 80 Soder-Wick<sup>®</sup> Rosin, SD Bobbin
- 60 Soder-Wick<sup>®</sup> No Clean, SD Bobbin
- 70 Soder-Wick<sup>®</sup> Unfluxed
- 75 Soder-Wick<sup>®</sup> Unfluxed, SD Bobbin

### *VacuPak<sup>™</sup> Packaging*

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

### HELPFUL HINTS:

**Water Soluble Users:** Use Soder-Wick<sup>®</sup> Unfluxed **70** or **75** Series to dip in water soluble flux and then desolder normally.

**Ball Grid Array:** Use Soder-Wick<sup>®</sup> BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

**NOTE:** This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW CHEMTRONICS<sup>®</sup> does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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